

特征 Features

- 表面安装应用 For surface mount applications
- 玻璃钝化芯片 Glass passivated junction
- 快速响应时间 Very fast response time
- 优良钳位能力 Excellent clamping capability
- 最高焊接温度 260°C/10 秒

High temperature soldering guaranteed:

- 260°C/10 seconds at terminals
- 200W 峰值脉冲保护能力(≥60V 为 175W)
- 200W peak pulse power capability (175W above 60V)
- 10/1000μs 波形, 重复率:0.01%
- a 10/1000μs waveform, repetition rate (duty cycle): 0.01%

机械数据 Mechanical Data

- 封装: 塑料封装 Case: Molded plastic body
- 端子: 焊料被镀 Terminals: Solder plated
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 安装位置: 任意 Mounting Position: Any
- 重量: 0.016克 Weight: 0.016 gram

极限值和温度特性 $T_A = 25^\circ\text{C}$ 除非另有规定。

Maximum Ratings & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
最大峰值脉冲功率 Peak pulse power dissipation with a 10/1000μs waveform ^(1, 2) (see fig. 1)	P_{PPM}	200	W
最大峰值脉冲电流 Peak pulse current with a 10/1000μs waveform ⁽¹⁾	I_{PPM}	See Next Table	A
正向峰值浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3ms single half sine-wave uni-directional only ⁽²⁾	I_{FSM}	20	A
典型热阻 Typical thermal resistance ⁽³⁾	$R_{\theta JA}$	180	°C/W
工作结温和存储温度 Operating junction and storage temperature range	T_J, T_{STG}	-55---+150	°C

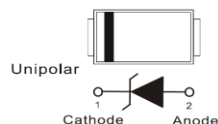
Notes: (1) Non-repetitive current pulse, per Fig. 3 and derated above $T_A = 25^\circ\text{C}$ per Fig. 2. Rating is 175W above 60V

(2) Mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pads to each terminal

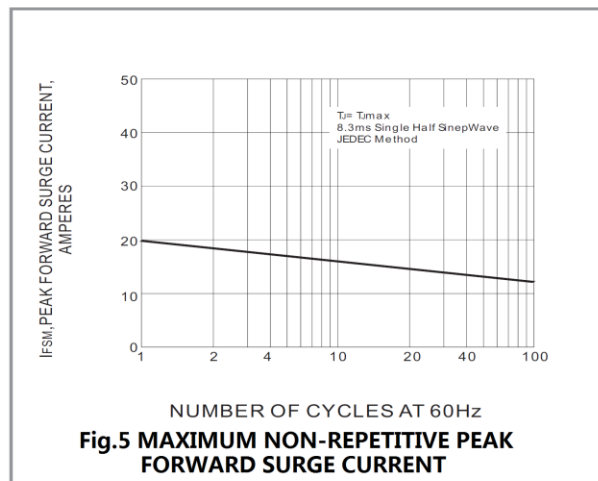
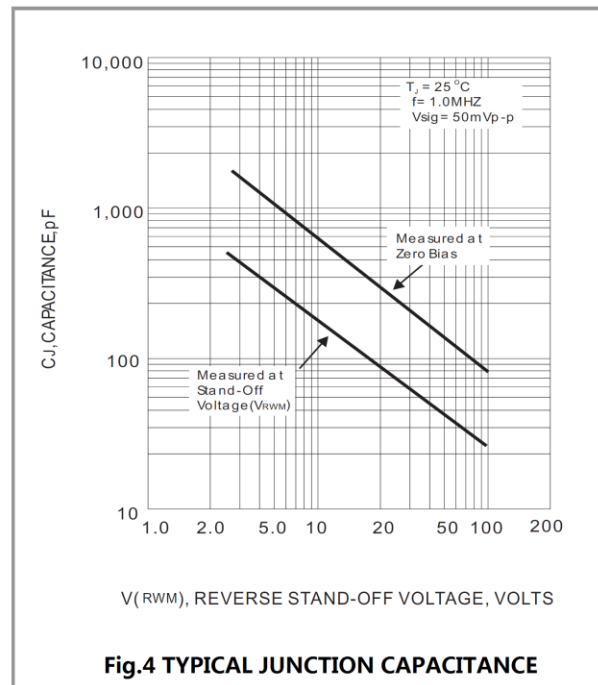
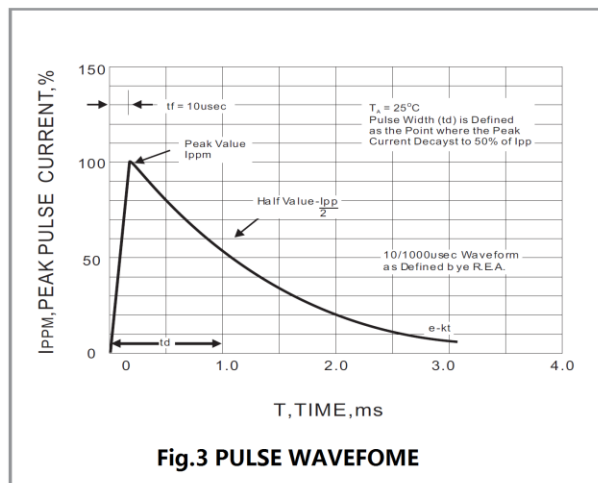
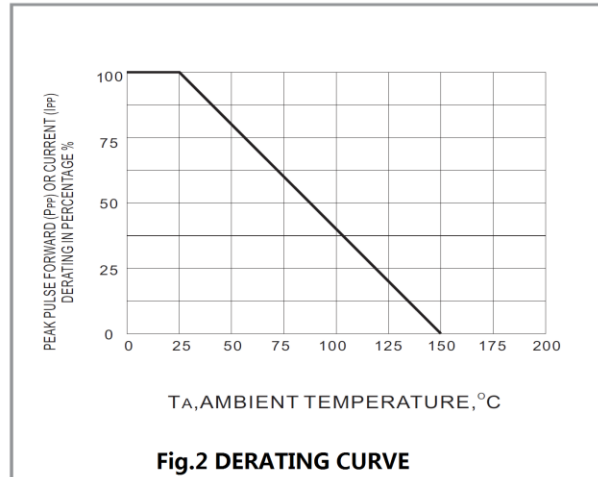
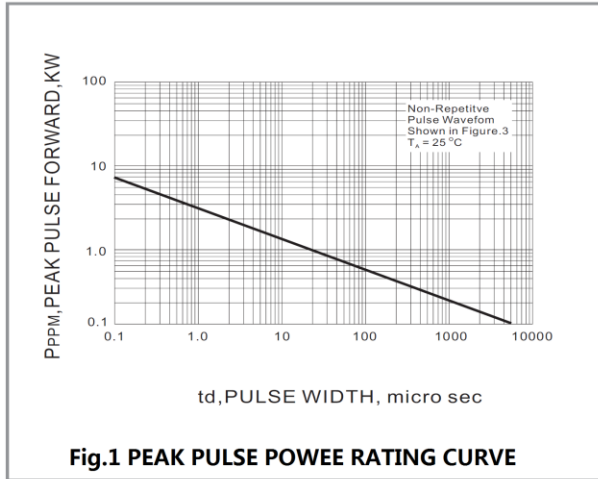
(3) Mounted on minimum recommended pad layout

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified)

Part Number	V_{RWM}	$V_{BR}@I_T$			$I_R@V_{RWM}$	$V_C@I_{PP}$		Marking Code
		Min.	Max	I_T		V	A	
SMF3.3A	3.3	5.2	6.0	10	400	8	25	FD



Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified)



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[>>KUU\(永裕泰\)](#)